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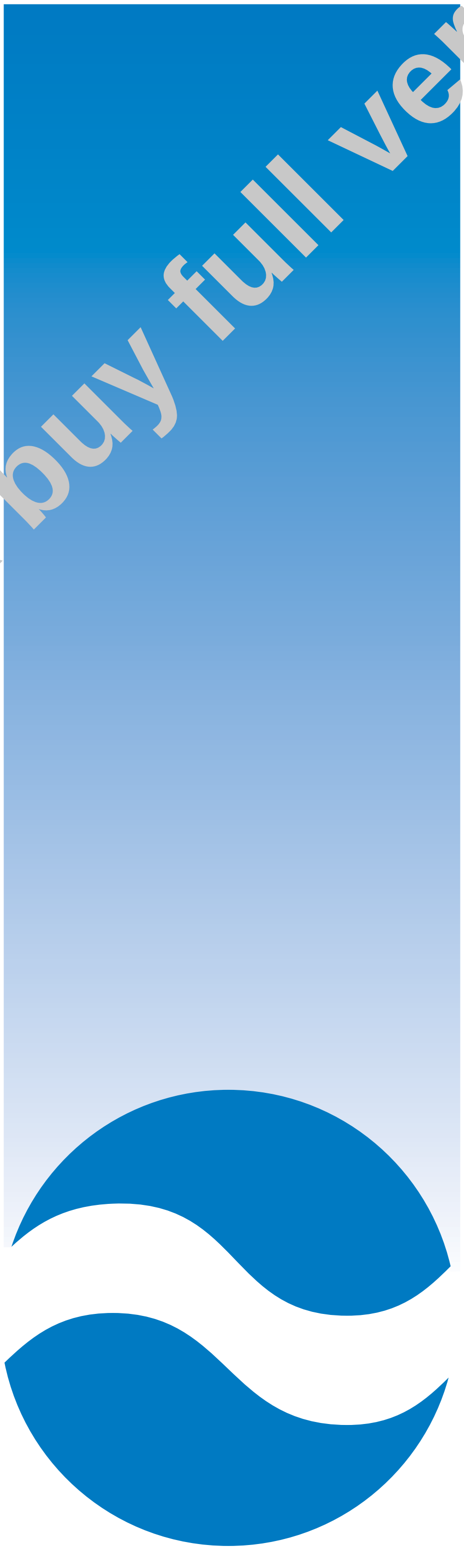
Space and Military Applications Electronic Hardware Addendum to IPC J-STD-001H Requirements for Soldered Electrical and Electronic Assemblies



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IPC J-STD-001HS

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Developed by the J-STD-001 Space and Military Electronic Assemblies Task Group (5-22as) of the Assembly & Joining Committee (5-20) of IPC

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Space and Military Applications Electronic Hardware Addendum to IPC J-STD-001H Requirements for Soldered Electrical and Electronic Assemblies

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